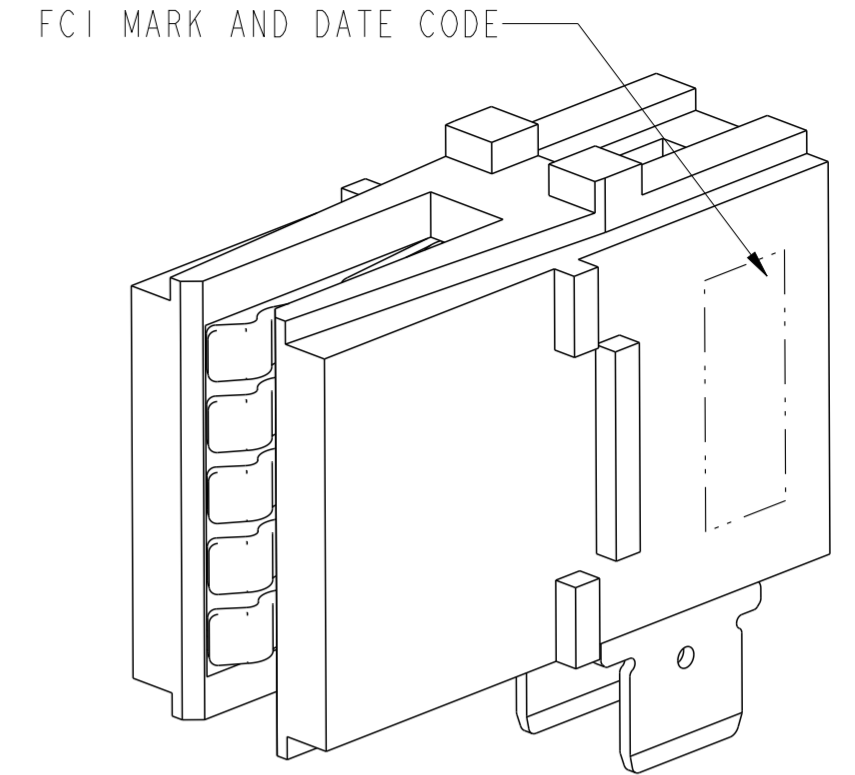
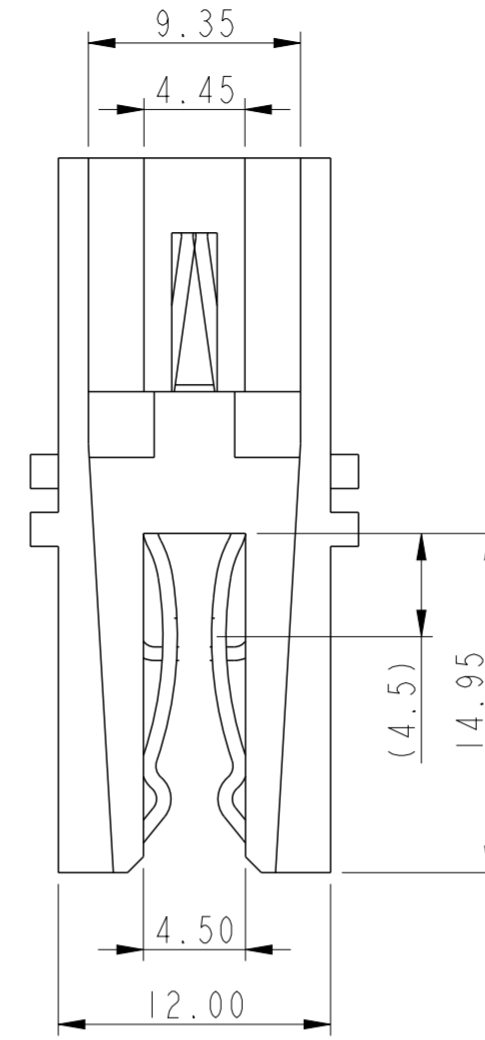
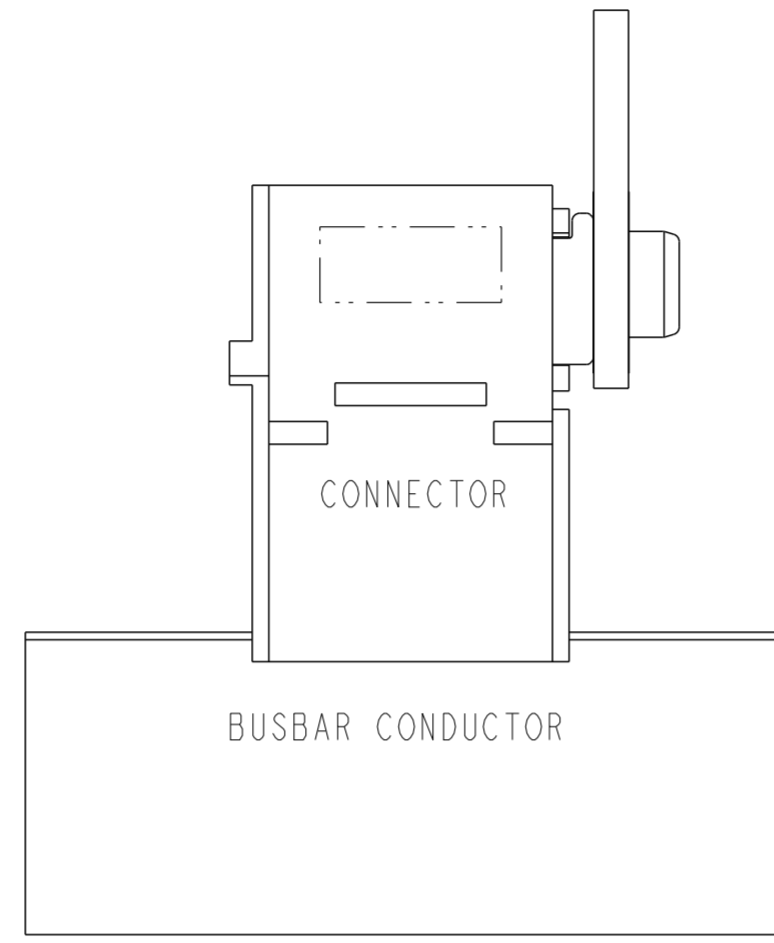
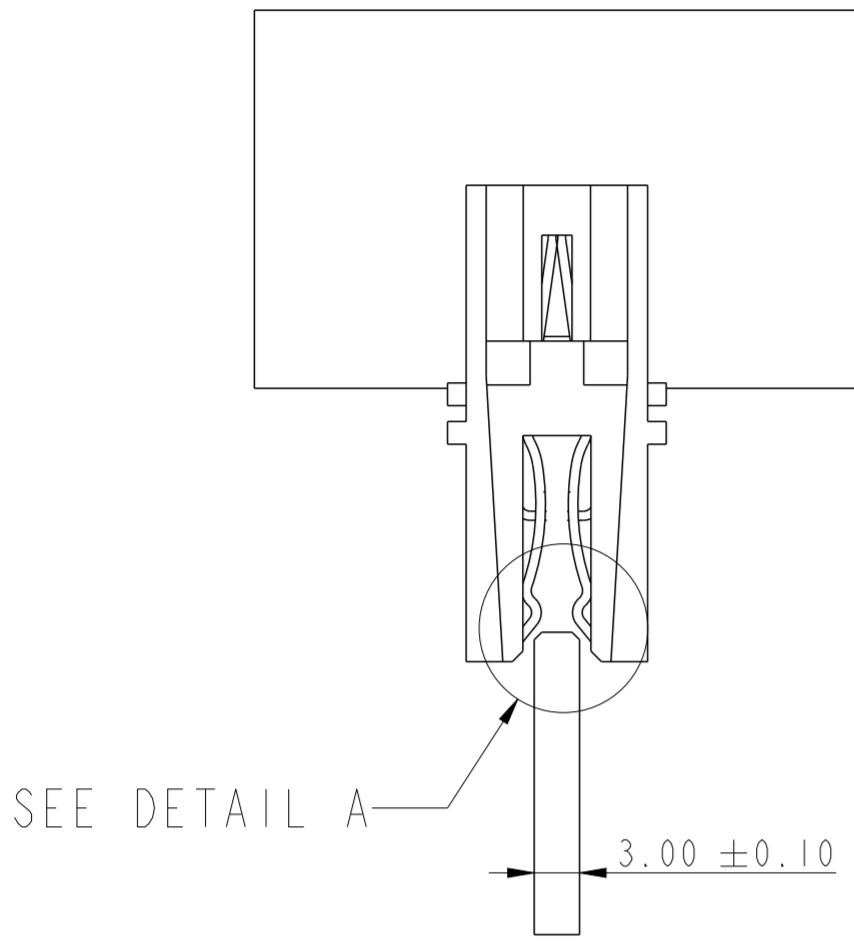
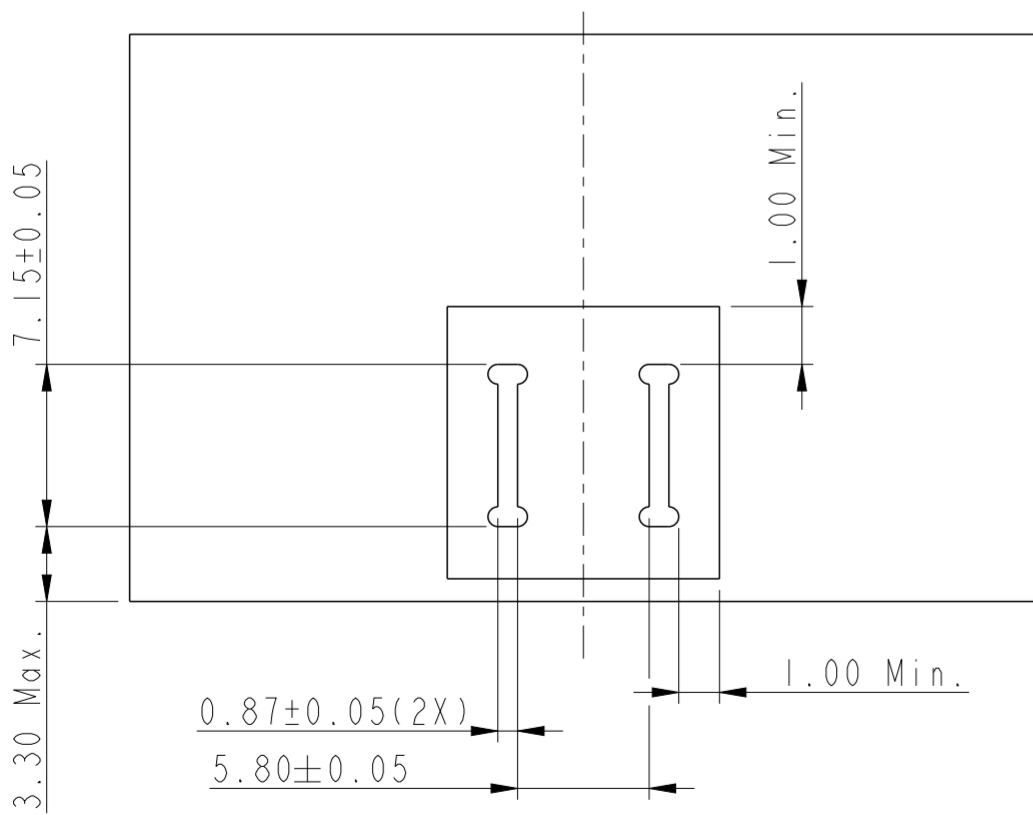
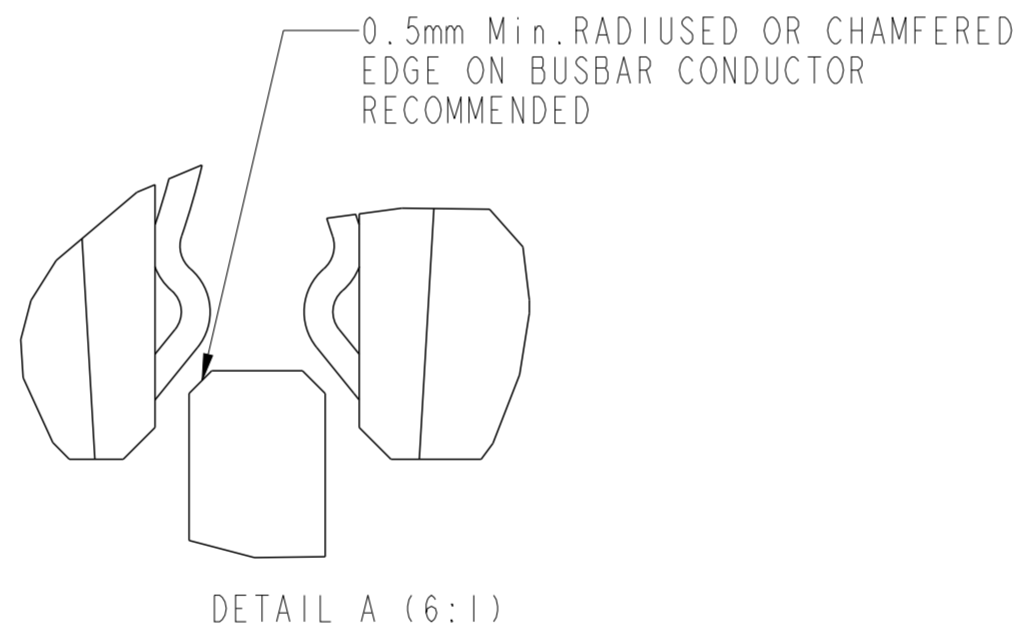


PRODUCT NUMBER	DESCRIPTION(PLATING)	Dim. A	Dim. B	PCB THICKNESS
10125600-S01LF	CONTACT AREA:AGT PLATING-3.0um SILVER OVER 1.27um NICKEL	5.68	2.70	4.80 Max.
10125600-S02LF	CONTACT AREA:AGT PLATING-3.0um SILVER OVER 1.27um NICKEL	4.40	4.00	2.00 Max.



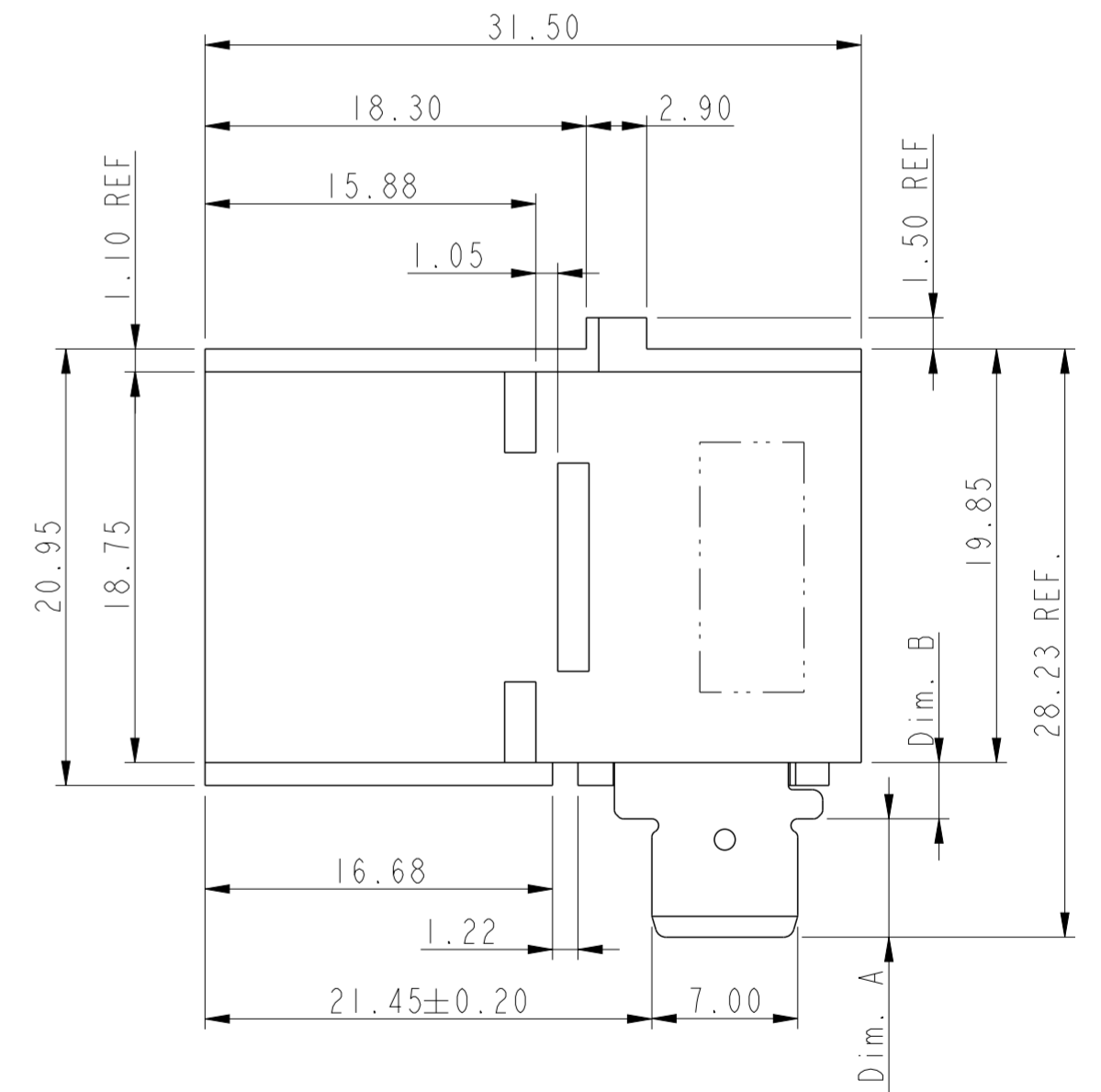
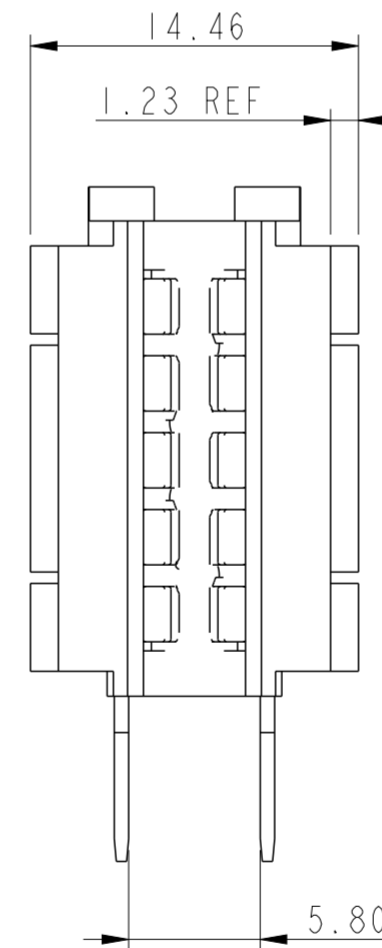
PCB AND BUSBAR-CONDUCTOR  
IN THESE VIEWS ARE SHOWN FOR REFERENCE ONLY.



RECOMMENDED PCB LAYOUT  
THICKNESS 4.8mm Max.

NOTES:

- CONNECTOR HOUSING:  
HIGH TEMPERATURE THERMOPLASTIC GLASS FILLED, UL 94V-0  
TERMINALS: COPPER ALLOY
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECOND IN A WAVE SOLDER APPLANTION WITH CIRCUIT BOARD.
- FINISHES:  
SEE PRODUCT NUMBER
- PRODUCT SPECIFICATION: GS-12-1179  
APPLICATION SPECIFICATION: GS-20-0396  
PACKING SPECIFICATION: GS-14-2376
- THE CONNECTOR MUST BE SUPPORTED WITH A FIXTURE DURING WAVE SOLDERING PROCESS



spec ref	-	dr	Zhao Peter	2013/06/20	projection	MM	size	A2	scale	3:1
tolerance std	ISO 406 ISO 1101	eng	Jacklin Zou	2017/06/22		← →	ecn no	ELX-DG-27194-1		
surface	-	chr	-	rel level				Released		
		appr	Pei-Ming Zheng	2017/06/28	product family		rel level	Released		
		linear	0.X	±0.30	Amphenol FCI		title	Solder Tab		
			0.XX	±0.25	www.fci.com		part no.	Barklip R/A CONNECTOR		
		angular	0°	±2°	cat. no.		Product - Customer Drw	sheet 1 of 1		